## **AMENDMENT**

Please cancel claims 1-24 without prejudice.

Please add the following new claims:

Claim 25 (newly presented) 25. A curing light comprising:

a wand adapted to be grasped by a human hand for use in positioning and manipulating the curing light,

a light module attached to said wand,

said light module including an elongate heat sink with a proximal end and a distal end, said proximal end being proximate said wand, said elongate heat sink having a longitudinal axis,

a mounting platform located at said elongate heat sink distal end, said mounting platform being adapted to have a LED chip module, and

an LED chip module mounted on said mounting platform, said LED chip module including

a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

a well on said primary heat sink for mounting an LED chip,

an LED chip mounted in said well,

a cover that provides protective covering for said LED chip and which permits light emitted by said LED chip to pass through it to provide usable light exiting from said light module;

wherein said LED chip module is mounted on said mounting platform so at least some that light emitted by said LED chip module travels away from said LED chip module in a linear direction that represents an angle with respect to said elongate heat sink longitudinal axis in the range of 30 to 150 degrees.

Claim 26 (newly presented) 26. A curing light comprising:

an elongate heat sink with a proximal end and a distal end, said elongate heat sink having a longitudinal axis defined between said proximal end and said distal end,

an LED chip module mounted at said elongate heat sink distal end. said LED chip module including

61

a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

a well on said primary heat sink for mounting an LED chip,

an LED chip mounted in said well,

a cover that provides protective covering for said LED chip and which permits light emitted by said LED chip to pass through it to provide usable light exiting from said light module;

wherein said LED chip module is mounted on said mounting platform so at least some that light emitted by said LED chip module travels away from said LED chip module in a linear direction that represents an angle with respect to said elongate heat sink longitudinal axis in the range of 30 to 150 degrees.

Claim 27 (newly presented) 27. A curing light as recited in claim 26 wherein said LED chip is mounted in said well by use of a heat conductive adhesive.

Claim 28 (newly presented) 28. A curing light as recited in claim 26 wherein said LED chip is mounted in said well by use of a light reflective adhesive.

Claim 29 (newly presented) 29. A curing light as recited in claim 26 wherein said well has a reflective wall.

Claim 30 (newly presented) 30. A curing light as recited in claim 29 wherein said reflective wall includes a material selected from the group consisting of AI, Au, Ag, Zn, Cu, Pt, chrome, metal, plating and plastic.

Claim 31 (newly presented) 31. A curing light comprising:

an elongate heat sink with a proximal end and a distal end, said elongate heat sink having a longitudinal axis defined between said proximal end and said distal end,

a semiconductor chip capable of emitting light that can be used to facilitate a curing process;

wherein said semiconductor chip is fixedly mounted with respect to said elongate heat sink so at least some that light emitted by said semiconductor chip travels away from said semiconductor chip module in a linear direction that represents an angle with respect to said elongate heat sink longitudinal axis in the range of 30 to 150 degrees.

Claim 32 (newly presented) 32. A curing light comprising:

a wand with a proximal end and a distal end, said wand having a longitudinal axis defined between said proximal end and said distal end,

- a heat sink for drawing heat away from a semiconductor chip,
- a semiconductor chip capable of emitting light that can be used to facilitate a curing process;

wherein said semiconductor chip is fixedly mounted with respect to wand so at least some that light emitted by said semiconductor chip travels away from said semiconductor chip in a direction that represents an angle with respect to said wand longitudinal axis in the range of 30 to 150 degrees.

Claim 33 (newly presented) 33. A curing light comprising:

- a handle with a proximal end and a distal end, said wand having a longitudinal axis defined between said proximal end and said distal end,
  - a heat sink for drawing heat away from a semiconductor chip,
- a semiconductor chip capable of emitting light that can be used to facilitate a curing process;

wherein said semiconductor chip is fixedly mounted with respect to handle so at least some that light emitted by said semiconductor chip travels away from said semiconductor chip in a direction that represents an angle with respect to said handle longitudinal axis in the range of 30 to 150 degrees.

## **LISTING OF CLAIMS:**

- 1. (cancelled)
- 2. (cancelled)
- 3. (cancelled)
- 4. (cancelled)
- 5. (cancelled)
- 6. (cancelled)
- 7. (cancelled)
- 8. (cancelled)
- 9. (cancelled)
- 10. (cancelled)
- 11. (cancelled)
- 12. (cancelled)
- 13. (cancelled)
- 14. (cancelled)
- 15. (cancelled)
- 16. (cancelled)
- 17. (cancelled)
- 18. (cancelled)
- 19. (cancelled)
- 20. (cancelled)
- 21. (cancelled)
- 22. (cancelled)
- 23. (cancelled)
- 24. (cancelled)

Claim 25 (newly presented) 25. A curing light comprising:

- a wand adapted to be grasped by a human hand for use in positioning and manipulating the curing light,
- a light module attached to said wand,

said light module including an elongate heat sink with a proximal end and a distal end, said proximal end being proximate said wand, said elongate heat sink having a longitudinal axis,

a mounting platform located at said elongate heat sink distal end, said mounting platform being adapted to have a LED chip module, and

an LED chip module mounted on said mounting platform, said LED chip module including

a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

a well on said primary heat sink for mounting an LED chip,

an LED chip mounted in said well,

a cover that provides protective covering for said LED chip and which permits light emitted by said LED chip to pass through it to provide usable light exiting from said light module;

wherein said LED chip module is mounted on said mounting platform so at least some that light emitted by said LED chip module travels away from said LED chip module in a linear direction that represents an angle with respect to said elongate heat sink longitudinal axis in the range of 30 to 150 degrees.

Claim 26 (newly presented) 26. A curing light comprising:

an elongate heat sink with a proximal end and a distal end, said elongate heat sink having a longitudinal axis defined between said proximal end and said distal end,

an LED chip module mounted at said elongate heat sink distal end. said LED chip module including

a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

a well on said primary heat sink for mounting an LED chip,

an LED chip mounted in said well,

a cover that provides protective covering for said LED chip and which permits light emitted by said LED chip to pass through it to provide usable light exiting from said light module;

wherein said LED chip module is mounted on said mounting platform so at least some that light emitted by said LED chip module travels away from said LED chip module in a linear direction that represents an angle with respect to said elongate heat sink longitudinal axis in the range of 30 to 150 degrees.

Claim 27 (newly presented) 27. A curing light as recited in claim 26 wherein said LED chip is mounted in said well by use of a heat conductive adhesive.

Claim 28 (newly presented) 28. A curing light as recited in claim 26 wherein said LED chip is mounted in said well by use of a light reflective adhesive.

Claim 29 (newly presented) 29. A curing light as recited in claim 26 wherein said well has a reflective wall.

Claim 30 (newly presented) 30. A curing light as recited in claim 29 wherein said reflective wall includes a material selected from the group consisting of Al, Au, Ag, Zn, Cu, Pt, chrome, metal, plating and plastic.

Claim 31 (newly presented) 31. A curing light comprising:

an elongate heat sink with a proximal end and a distal end, said elongate heat sink having a longitudinal axis defined between said proximal end and said distal end,

a semiconductor chip capable of emitting light that can be used to facilitate a curing process;

wherein said semiconductor chip is fixedly mounted with respect to said elongate heat sink so at least some that light emitted by said semiconductor chip travels away from said semiconductor chip module in a linear direction that represents an angle with respect to said elongate heat sink longitudinal axis in the range of 30 to 150 degrees.

Claim 32 (newly presented) 32. A curing light comprising:

- a wand with a proximal end and a distal end, said wand having a longitudinal axis defined between said proximal end and said distal end,
  - a heat sink for drawing heat away from a semiconductor chip,
- a semiconductor chip capable of emitting light that can be used to facilitate a curing process;

wherein said semiconductor chip is fixedly mounted with respect to wand so at least some that light emitted by said semiconductor chip travels away from said semiconductor chip in a direction that represents an angle with respect to said wand longitudinal axis in the range of 30 to 150 degrees.

Claim 33 (newly presented) 33. A curing light comprising:

a handle with a proximal end and a distal end, said wand having a longitudinal axis defined between said proximal end and said distal end,

a heat sink for drawing heat away from a semiconductor chip,

a semiconductor chip capable of emitting light that can be used to facilitate a curing process;

wherein said semiconductor chip is fixedly mounted with respect to handle so at least some that light emitted by said semiconductor chip travels away from said semiconductor chip in a direction that represents an angle with respect to said handle longitudinal axis in the range of 30 to 150 degrees.